Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Toshihide NABATAME	11/11/2008
Kunihiko IWAMOTO	11/11/2008
Yuuichi KAMIMUTA	11/10/2008

RECEIVING PARTY DATA

Name:	Renesas Technology Corp.
Street Address:	6-2, Otemachi 2-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	100-0004

Name:	Rohm Co., Ltd.
Street Address:	21, Saiin Mizosaki-cho, Ukyo-ku
City:	Kyoto-shi, Kyoto
State/Country:	JAPAN
Postal Code:	615-8585

Name:	Kabushiki Kaisha Toshiba
Street Address:	1-1, Shibaura 1-chome, Minato-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	105-8001

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12329580

CORRESPONDENCE DATA

PATENT REEL: 021942 FRAME: 0774

500724702

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Fax Number: (703)610-8686

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Correspondent Name: Mitchell W. Shapiro

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ATTORNEY DOCKET NUMBER: XA-11244/T3381-15941US01

NAME OF SUBMITTER: Mitchell W. Shapiro

Total Attachments: 3

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> PATENT REEL: 021942 FRAME: 0775

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., Rohm Co., Ltd. and Kabushiki Kaisha Toshiba, corporations organized under the laws of Japan,

located at 6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo 100-0004, Japan,

- 21, Saiin Mizosaki-cho, Ukyo-ku, Kyoto-shi, Kyoto 615-8585, Japan and
- 1-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8001, Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said

Renesas Technology Corp., Rohm Co., Ltd. and Kabushiki Kaisha Toshiba,

their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD OF THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Technology Corp., Rohm Co., Ltd. and Kabushiki Kaisha Toshiba,

their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp., Rohm Co., Ltd. and Kabushiki Kaisha Toshiba,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)

(発明者フルネームサイン)	(署名日)
1) Joshihide Nabatame (Toshihide NABAT	AME) November 11, 2008
2) (Kunihiko IWAN	юто)
3) (Yuuichi KAMIN	IUTA)
4)	
5)	
6)	

PATENT REEL: 021942 FRAME: 0776

Date Signed

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Signed on the date(s) indicated aside our signatures:

	inventor(s) (発明者フルネームサイン)	Date Signed (署名日)
1)_	(Toshihide NABATAME)	
2)_	Kurihiko Iwamoto (Kunihiko IWAMOTO)	11/11/2008
3) _	(Yuuichi KAMIMUTA)	
4)_		
5)_		
6)		

PATENT REEL: 021942 FRAME: 0777

ASSIGNMENT

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Signed on the date(s) indicated aside our signatures:

INVENTOH(S) (発明者フルネームサイン)		Date Signed (署名日)	
1)	(Toshihide NABATAME)		
2)	(Kunihike IWAMOTO)		
3)	Yulichi Kanimuta (Vuulchi KAMIMUTA)	11/10/2008	
4)			
5)			
6)			

PATENT REEL: 021942 FRAME: 0778

RECORDED: 12/09/2008